

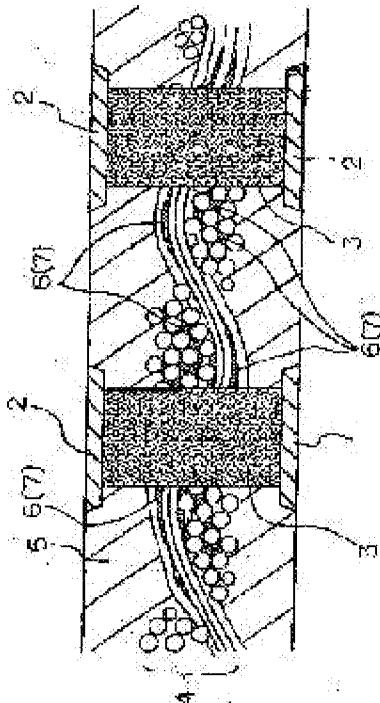
PATENT ABSTRACTS OF JAPAN

(11)Publication number : **2002-111215**
(43)Date of publication of application : **12.04.2002**

(51)Int.Cl. H05K 3/46
C08J 5/08
H01L 23/14
H05K 1/11
H05K 3/40
// C08L 63:00

(21)Application number : **2000-296946** (71)Applicant : **KYOCERA CORP**
(22)Date of filing : **28.09.2000** (72)Inventor : **HAYASHI KATSURA**
MATSUOKA TAKAHIRO
TATENO SHUICHI
FUJISAKI AKIYA

(54) WIRING BOARD AND ITS MANUFACTURING METHOD



(57) Abstract:

PROBLEM TO BE SOLVED: To provide a wiring board which contains insulating layers made of a composite material of a heat-resistant woven fabric and a thermosetting resin and has superior insulation reliability between via hole conductors even when the conductors are formed at narrow intervals of $\leq 500 \mu\text{m}$, and to provide a method of manufacturing the board.

SOLUTION: The wiring board is provided with the insulating layers 1 made of a composite material composed of the heat-resistant woven fabric 4, such as the glass woven fabric, etc., and the thermosetting resin 5, a plurality of conductor circuit layers 2 formed on and between the insulating layers 1, and the via hole conductors 3 which are formed by impregnating metallic powder packed in via holes with conductor paste so that the minimum interval between the conductors 3 may become $\leq 500 \mu\text{m}$. Before the

metallic powder is impregnated with the conductor paste, a liquid resin 7 is impregnated

into and cured in the voids 6 among the fibers of the heat-resistant woven fabric 4 around the via hole conductors 3.